



Material Content Data Sheet



Sales Product Name		IPD60R1K0CE		Issued		19. July 2018		
MA#		MA001581864						
Package		PG-TO252-3-343		Weight*		312.07 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.144	0.69	0.69	6869	6869
leadframe	non noble metal	iron	7439-89-6	0.137	0.04		440	
	inorganic material	phosphorus	7723-14-0	0.041	0.01		132	
	non noble metal	copper	7440-50-8	137.105	43.94	43.99	439338	439910
wire	non noble metal	aluminium	7429-90-5	4.637	1.49	1.49	14859	14859
encapsulation	organic material	carbon black	1333-86-4	1.289	0.41		4130	
	plastics	epoxy resin	-	24.489	7.85		78473	
	inorganic material	silicondioxide	60676-86-0	103.113	33.04	41.30	330414	413017
leadfinish	non noble metal	tin	7440-31-5	3.834	1.23	1.23	12284	12284
solder	noble metal	silver	7440-22-4	0.056	0.02		180	
	non noble metal	tin	7440-31-5	0.045	0.01		144	
	non noble metal	lead	7439-92-1	2.144	0.69	0.72	6871	7195
heatspreader	non noble metal	iron	7439-89-6	0.033	0.01		106	
	inorganic material	phosphorus	7723-14-0	0.010	0.00		32	
	non noble metal	copper	7440-50-8	32.995	10.57	10.58	105728	105866
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com